Dual N-Channel Enhancement Mode MOSFET

Features

- AEC-Q101 Qualified
- Low RDS(ON)
- Fully Characterized Capacitance and Avalanche
- Halogen and Antimony Free(HAF), RoHS compliant

Application

- Synchronous Rectification
- BLDC Motor drive applications
- Battery powered circuits

Key Parameters(Q1/Q2)

Parameter	Value	Unit		
BV _{DSS}	100	V		
Dearen Max	21 @ V _{GS} = 10 V			
R _{DS(ON)} Max	26 @ V _{GS} = 4.5 V	mΩ		
V _{GS(th)} typ	1.9	V		
Q _g typ	22 @ V _{GS} = 10 V	nC		

Absolute Maximum Ratings (at T_a = 25°C unless otherwise specified)(Q1\Q2)

Parameter	Symbol	Value	Unit			
Drain-Source Voltage	V _{DS}	100	V			
Gate-Source Voltage	V _{GS}	± 20	V			
Continuous Drain Current	lD	34 21	A			
Peak Drain Current, Pulsed ¹⁾	I _{DM}	130	А			
Avalanche Current	I _{AS}	18.5	А			
Single Pulse Avalanche Energy 2)	Eas	17	mJ			
Power Dissipation	P _{tot}	32.7	W			
Operating Junction and Storage Temperation	TJ, Tstg	- 55 to + 150	°C			

Thermal Characteristics(Q1\Q2)

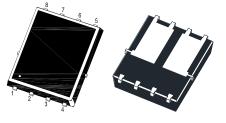
Parameter	Symbol	Max.	Unit	
Thermal Resistance from Junction to Case	Rejc	3.8	°C/W	
Thermal Resistance from Junction to Ambient ³⁾	Reja	80	°C/W	

¹⁾ Pulse Test: Pulse Width \leq 100 µs, Duty Cycle \leq 2%, Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.

 $^{2)}$ Limited by $T_{J(MAX)},$ starting T_{J} = 25 °C, L = 0.1 mH, R_{g} = 25 $\Omega,$ I_{AS} = 18.5 A, V_{GS} = 10 V.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.





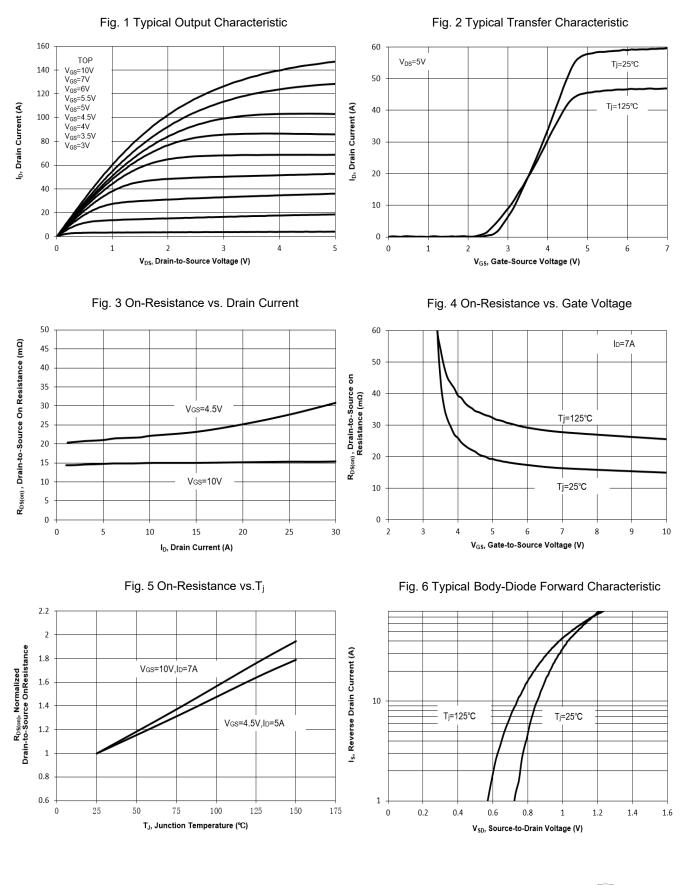
1.Source1 2.Gate1 3.Source2 4.Gate2 5.Drain2 6.Drain2 7.Drain1 8.Drain1 DFN5060 Plastic Package

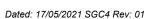
Characteristics at T_a = 25°C unless otherwise specified(Q1\Q2)

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at I⊳ = 250 µA	BV _{DSS}	100	-	-	V
Drain-Source Leakage Current at V _{DS} = 80 V	IDSS	-	-	1	μA
Gate Leakage Current at V _{GS} = ± 20 V	lgss	-	-	± 100	nA
Gate-Source Threshold Voltage at V _{DS} = V _{GS} , I _D = 250 μA	$V_{GS(th)}$	1.2	-	2.5	V
Drain-Source On-State Resistance at V_{GS} = 10 V, I_D = 7 A at V_{GS} = 4.5 V, I_D = 5 A	$R_{DS(on)}$	-	15 -	21 26	mΩ
DYNAMIC PARAMETERS					
Forward Transconductance at V_{DS} = 5 V, I_D = 7 A	g fs	-	15.8	-	S
Gate resistance at V_{DS} = 0 V, f = 1 MHz	Rg	-	0.6	-	Ω
Input Capacitance at V _{GS} = 0 V, V _{DS} = 50 V, f = 1 MHz	Ciss	-	1028	-	pF
Output Capacitance at V _{GS} = 0 V, V _{DS} = 50 V, f = 1 MHz	Coss	-	170	-	pF
Reverse Transfer Capacitance at V _{GS} = 0 V, V _{DS} = 50 V, f = 1 MHz	Crss	-	7	-	pF
Gate charge total at V_{DS} = 50 V, V_{GS} = 10 V, I_D = 7 A at V_{DS} = 50 V, V_{GS} = 4.5 V, I_D = 7 A	Qg	-	22 12	-	nC
Gate to Source Charge at V_{DS} = 50 V, V_{GS} = 10 V, I_D = 7 A	Q _{gs}	-	4	-	nC
Gate to Drain Charge at V_{DS} = 50 V, V_{GS} = 10 V, I_D = 7 A	Q _{gd}	-	6	-	nC
Turn-On Delay Time at V _{DS} = 50 V, V _{GS} = 10 V, I _D = 7 A, R _g = 4.7 Ω	t _{d(on)}	-	12	-	nS
Turn-On Rise Time at V _{DS} = 50 V, V _{GS} = 10 V, I _D = 7 A, R _g = 4.7 Ω	tr	-	3.5	-	nS
Turn-Off Delay Time at V _{DS} = 50 V, V _{GS} = 10 V, I _D = 7 A, R _g = 4.7 Ω	$t_{d(off)}$	-	11	-	nS
Turn-Off Fall Time at V _{DS} = 50 V, V _{GS} = 10 V, I _D = 7 A, R _g = 4.7 Ω	t _f	-	4	-	nS
Body-Diode PARAMETERS			-		
Drain-Source Diode Forward Voltage at I_S = 1 A, V_{GS} = 0 V	V_{SD}	-	-	1.2	V
Body-Diode Continuous Current	ls	-	-	34	Α
Body-Diode Continuous Current, Pulsed	Ism	-	-	130	А
Body Diode Reverse Recovery Time at Is = 7 A, di/dt = 100 A / μs	t _{rr}	-	40	-	nS
Body Diode Reverse Recovery Charge at I _S = 7 A, di/dt = 100 A / μs	Qrr	-	30	-	nC



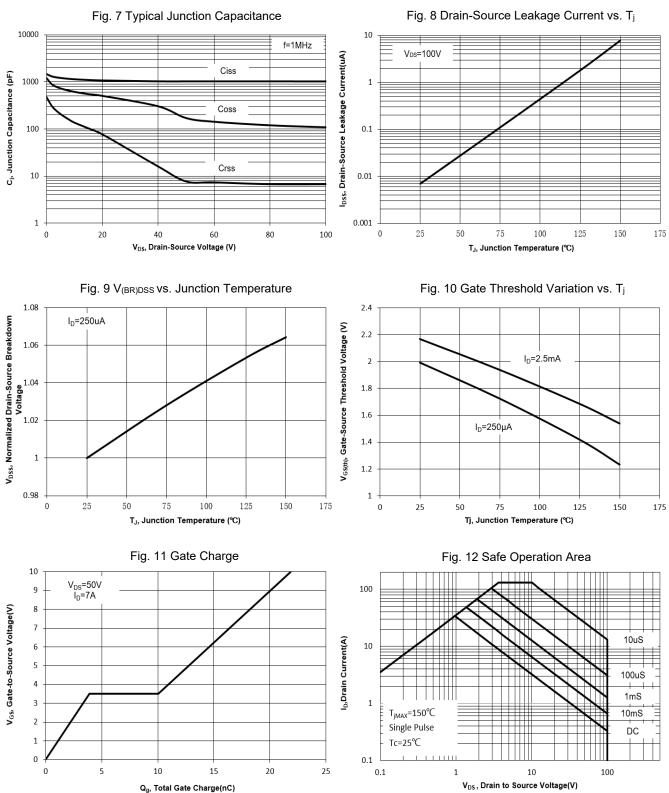
Electrical Characteristics Curves(Q1/Q2)





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Electrical Characteristics Curves(Q1/Q2)





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Electrical Characteristics Curves(Q1/Q2)

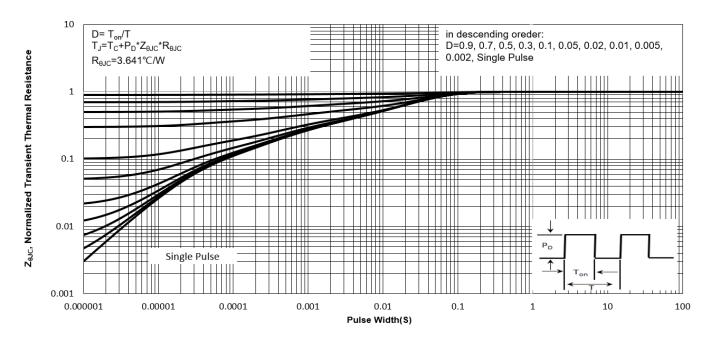
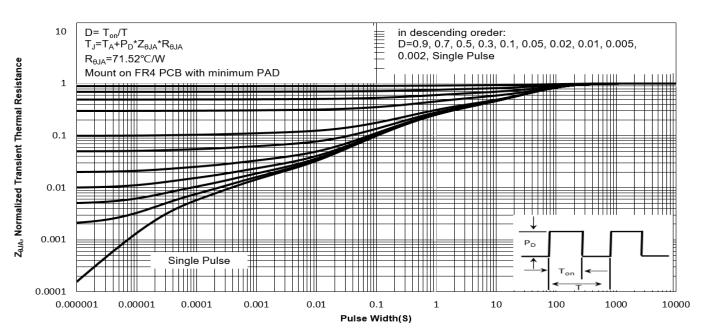


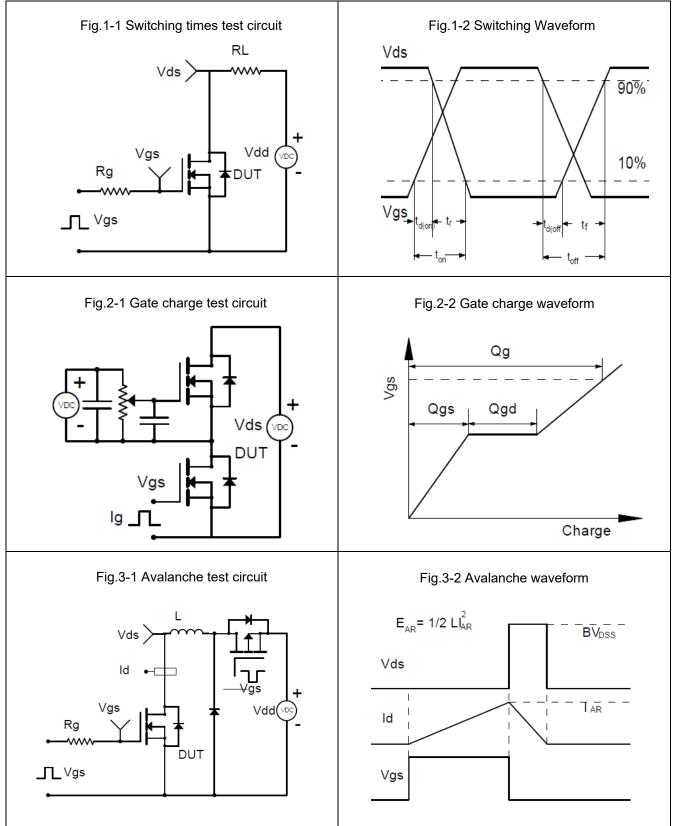


Fig. 14 Normalized Maximum Transient Thermal Impedance(z_{OJA})





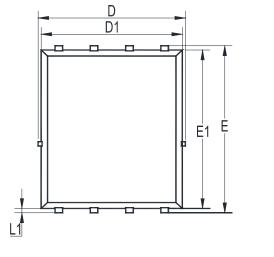
Test Circuits(Q1/Q2)

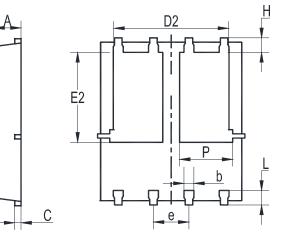




Package Outline Dimensions (Units: mm)

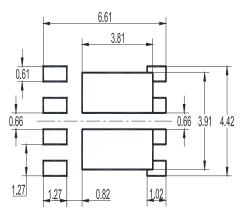
DFN5060





Unit	А	b	С	D	D1	D2	Е	E1	E2	е	L	L1	Н	Р
mm	1.12	0.51	0.34	5.26	5.1	4.5	6.25	6	3.66	1.37	0.71	0.2	0.71	2.3
	0.9	0.33	0.11	4.7	4.7	3.56	5.75	5.6	3.18	1.17	0.35	0.06	0.35	1.7

Recommended Soldering Footprint



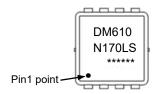
Packing information

Packago		Tape Width	Pit	ch	Reel	Size	Per Reel Packing Quantity
	Package	(mm)	mm	inch	mm	inch	Fei Neel Facking Quantity
	DFN5060	12	8 ± 0.1	0.315 ± 0.004	330	13	5,000

Marking information

- " DM610N170LS " = Part No.
- " ****** " = Date Code Marking

Font type: Arial





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